In the Claims

Please cancel claims 11-20 and 36-40, without prejudice or disclaimer, seeking to place the application in condition for immediate formal allowance.

The following listing of claims will replace all prior versions of the claims in this application.

Listing of Claims

Claims 1-30 (cancelled)

Claim 31 (currently amended): The method of reducing electromagnetic interference generated within an integrated circuit device package wherein the integrated circuit device package comprises

a wafer having wafer circuitry disposed thereon;

a plurality of conductors defining electrically conductive paths for carrying the electric current flowing to and from the wafer circuitry; and

a structure that encapsulates and supports the wafer, said structure comprises an encapsulating medium;

said method comprising [applying] introducing into the encapsulating medium a powder composed of ferrite magnetic material that exhibits a hysteresis loss, in the vicinity of at least one of the electrically conductive paths

such that the ferrite magnetic material does not itself prevent bending of the at least one of the electrically conductive paths, but serves to attenuate the highest frequency signal components while introducing generally little inductance effects of overshoot and ringing associated with the series inductance of the at least one of the electrically conductive paths.

Claim 32 (currently amended): The method of claim 31, wherein ~~the structure that encapsulates and supports the wafer comprises an encapsulating medium,~~ ~~and~~ said method further comprises introducing the [[a]] powder composed of ferrite magnetic material that exhibits a hysteresis loss characteristic ~~but essentially no eddy-current loss~~, into the encapsulating medium such that the powder composed of ferrite magnetic material does not carry any of the electric current flowing to and from the wafer circuitry, but serves to cause the series inductance of the at least one of the electrically conductive paths to behave as a lossy inductor so as to attenuate the highest frequency signal components while introducing generally little inductance effects of overshoot and ringing.

Claim 33 (currently amended): The method of claim 32, wherein a relatively small amount of the powder composed of ferrite magnetic material that exhibits a hysteresis loss characteristic ~~but essentially no eddy-current loss,~~ is introduced into the encapsulating medium such that the magnetic material does not carry any of the electric current flowing to and from the wafer circuitry, but so that the relative permeability in the vicinity of the at least one of the electrically conductive paths is not so high as to cause significant mutual coupling with other of the plurality of conductors.

Claim 34 (currently amended): The method of claim 33, where the introduction of the relatively small amount of the powder composed of ferrite magnetic material that exhibits a hysteresis loss characteristic ~~but essentially no eddy-current loss,~~ is such that the magnetic material does not carry any of the electric current flowing to and from the wafer circuitry, but results in a relative permeability of the encapsulating medium that is sufficient to desirably affect the series inductance of at least one of the electrically conductive paths.

Claim 35 (previously presented): The method of claim 33, where the mutual inductance between the one of the plurality of electrically conductive paths and an adjacent conductor is small with respect to the self-inductance of each conductor.